

# RF Inlay Smart Card Welding Head

This pressure welding head is designed for RF inlay smart card manufacturing. It ensures consistent and reliable bonding of RF components to smart card substrates.



## ADDITIONAL IMAGES



## Product Overview

### Precision Engineering for Smart Card Production

This pressure welding head is specifically engineered for the reliable bonding of RF inlays onto smart card substrates. Its design prioritizes optimal pressure distribution and precise alignment to ensure electrical conductivity and mechanical stability. Built from durable, high-quality materials, the unit is tailored for the rigorous demands of high-volume manufacturing environments.

## Technical Specifications

### Performance Metrics

**1 High**

Alignment Precision

**100 %**

Durability Rating

### Key Design Features

- Split design for optimal pressure distribution
- Integrated alignment holes for secure mounting
- High thermal conductivity materials
- Wear-resistant construction

## Compatibility & Usage

Ideal Applications	RF Inlay Welding, Smart Card Manufacturing, High-Volume Production
Equipment Compatibility	Yes